MATERIAL DECLARATION SHEET

BOURNS®

Package Type	PTVS3-xxxC-M		
Product Line	Semiconductor products		
Compliance Date	20th Jan 2017		
RoHS Compliant	Yes	MSL	Level 1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	2.3134	Amorphous Silica	60676-86-0	89.50	59.22	66.17
				Solid Epoxy Resin 1	Proprietary	3.20	2.12	
				Solid Epoxy Resin 2	Proprietary	2.40	1.59	
				Phenol Resin	Proprietary	4.10	2.71	
				Crystalline Silica	14808-60-7	0.50	0.33	
				Carbon Black	1333-86-4	0.30	0.20	
2	Leadframe	Copper Alloy	0.5920	Copper	7440-50-8	97.44	16.50	16.93
				Iron	7439-89-6	2.35	0.40	
				Other, not to declare	-	0.21	0.03	
3	Electrodes	Copper Alloy	0.3239	Copper	7440-50-8	99.50	9.21	9.26
				Other, not to declare	-	0.50	0.05	
4	Clip	Copper Alloy	0.1181	Copper	7440-50-8	99.50	3.36	3.38
				Other, not to declare	-	0.50	0.02	
5	Chip	Silicon	0.0737	Silicon	7440-21-3	89.01	1.88	2.11
				Aluminum	7429-90-5	4.19	0.09	
				Nickel	7440-02-0	6.49	0.13	
				Gold	7440-57-5	0.31	0.01	
6	Die Attach	Solder	0.0539	Lead*	7439-92-1	92.50	1.42	1.54
				Tin	7440-31-5	5.00	0.08	
				Silver	7440-22-4	2.50	0.04	
7	Terminal Finish	Tin	0.0213	Tin	7440-31-5	100.00	0.61	0.61
		Total Weight	3.4963					

*** 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)**

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society